NS PACKAGE

SOCS029B - AUGUST 1991

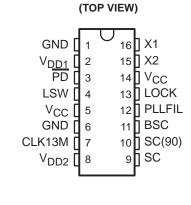
- Solid-State Reliability
- Surface-Mount Package

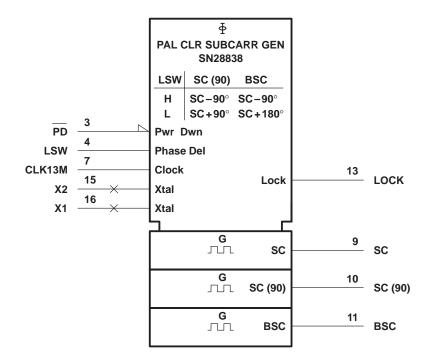
description

The SN28838 is a monolithic integrated circuit designed to interface with the SN28837 PAL-timing generator in order to generate the PAL-color timing signals. It receives inputs from the SN28837 and a 17-MHz oscillator and outputs the PAL-color subcarrier, color subcarrier delayed by 90 degrees, and burst-color-subcarrier signals, which are all 4.43-MHz outputs.

The SN28838 is supplied in a 16-pin surface-mount package and is characterized for operation from 0°C to 40°C.

logic symbol





This device contains circuits to protect its inputs and outputs against damage due to high static voltages or electrostatic fields. These circuits have been qualified to protect this device against electrostatic discharges (ESD) of up to 2 kV according to MIL-STD-883C, Method 3015; however, precautions should be taken to avoid application of any voltage higher than maximum-rated voltages to these high-impedance circuits. During storage or handling, the device leads should be shorted together or the device should be placed in

conductive foam. In a circuit, unused inputs should always be connected to an appropriate logic voltage level, preferably either V_{CC} or ground. Specific guidelines for handling devices of this type are contained in the publication *Guidelines for Handling Electrostatic-Discharge-Sensitive* (ESDS) Devices and Assemblies available from Texas Instruments.



Terminal Functions

TERMINAL		1/0	DECORIDATION				
NAME	NO.	I/O	DESCRIPTION				
BSC	11	0	Burst subcarrier				
CLK13M	7	ı	13.34-MHz clock from SN28837				
GND	1		Ground				
GND	6		Ground				
LOCK	13	0	PLL lock signal. LOCK is high when the phase-locked loop is locked.				
LSW	4	I	Line switch (from SN28837)				
PD	3	I	Power down				
PLLFIL	12		Terminal for PLL filter				
SC	9	0	Subcarrier				
SC(90)	10	0	Subcarrier 90° out of phase				
V _{CC} †	5		Power supply voltage				
∨ _{CC} †	14		Power supply voltage				
V _{DD1}	2		Power supply voltage for X1				
V_{DD2}	8		Power supply voltage for CLK13M				
X1	16		Crystal agaillator				
X2	15		Crystal oscillator				

[†] These two terminals should be connected together externally.

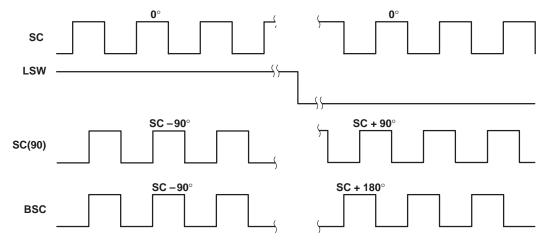


Figure 1. SC, SC(90), and BSC Timing

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absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V _{CC} (see Note 1)	0.3 V to 7 V
Input voltage range, V _I	\dots -0.3 V to V _{CC} + 0.3 V
Output voltage range, VO	$-0.3 \text{ V to V}_{CC} + 0.3 \text{ V}$
Operating free-air temperature range, T _A	–30°C to 75°C
Storage temperature range	–55°C to 125°C
Lead temperature 1,6 mm (1/16 inch) from case for 10 seconds	260°C
Continuous total power dissipation	200 mW

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

recommended operating conditions

	MIN	NOM	MAX	UNIT
Supply voltage, V _{CC}	4.5	5	5.5	V
High-level input voltage, V _{IH}	V _{CC} ×0.7			V
Low-level input voltage, V _{IL}			0.8	V
Operating frequency		17.735		MHz
Power-up time		300		μs
Operating free-air temperature, TA	-20		45	°C

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER			TEST CONDITIONS		MIN	TYP	MAX	UNIT
Vон	High-level output voltage	BSC, SC, SC(90)	$V_{CC} = 4.5 \text{ V},$	$I_{OH} = -2 \text{ mA}$	3.5			V
VOL	Low-level output voltage	BSC, SC, SC(90)	$V_{CC} = 4.5 \text{ V},$	$I_{OL} = 2 \text{ mA}$			0.5	V
lιΗ	High-level input current (except X1)‡		V _I = 5 V				100	nA
IIL	Low-level input current		V _I = 0		-30	-200	-370	μΑ
	Output frequency	BSC, SC, SC(90)				4.43		MHz
ICC	Supply current					5	20	mA

[‡] All inputs except X1 have pullup current sources.

switching characteristics

PARAMETER		TEST CONDITIONS	MIN	TYP	MAX	UNIT
t _r	Rise time	C _L = 50 pF		50		ns
t _f	Fall time			50		ns

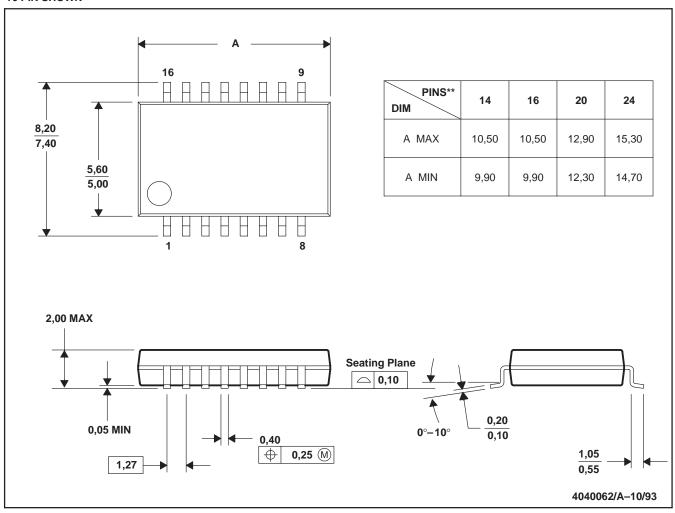
NOTES: 1. All voltage values are with respect to the GND terminal.

MECHANICAL DATA

NS/R-PDSO-G**

PLASTIC SMALL-OUTLINE PACKAGE

16 PIN SHOWN



NOTES: A. All linear dimensions are in millimeters.

- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion not to exceed 0,15.

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